

# EPIC-KB07

## Thermal Image Analysis Report

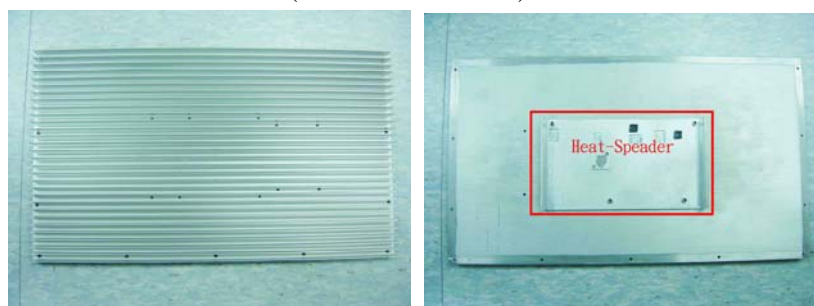
Summary	<input checked="" type="checkbox"/> <b>Pass</b> <input type="checkbox"/> <b>Fail</b> <input type="checkbox"/> <b>Pass with Deviation</b> <b>Comment:</b>			
	Test Result Summary			
	Critical	Major	Minor	Enhancement
Defect Found	0	0	0	0
Defect Unsolved	0	0	0	0

Issue date	Approval	Test Engineer
2014 / 05 / 22	Tom Lin	Juno Cheng

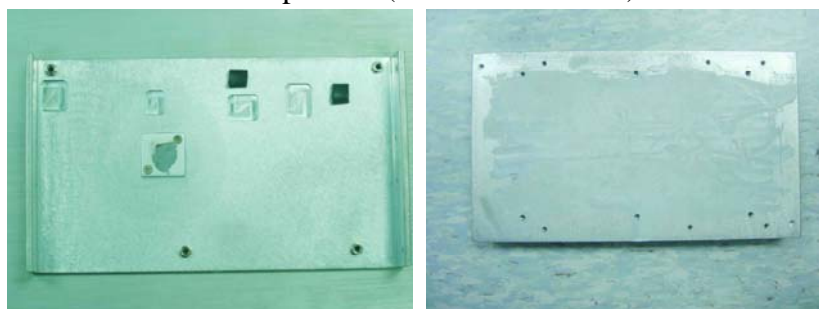
**Test Product: EPIC-KB07 A0.2****Sample Configuration & Quantity Under Test:**

- CPU : AMD eKABINI A6-5200 APU 2000MHz (Quad Core)
- Chipset: AMD SoC APU
- USB Flash: Transcend 8GB (For DOS Mode Power On/Off Test)
- Memory : DSL 4GB \* 1 / DDR3 1066 / SEC K4B1G0846G
- 3.5" SATA HDD : TOSHIBA DT01ACA050 / 500GB
- BIOS : Ver. R0.7(PKB7AM07)
- Test Software : Windows 7 / Run PassMark Burn In Test 7.1 Pro
- Power : Zippy HG2-6400P
- Heat Sink:

Heat sink(P/N: M169655000)



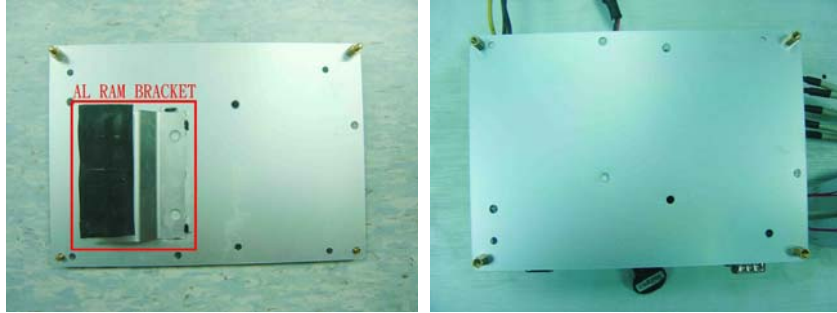
Heat-Spreader (P/N: M10KB07000)



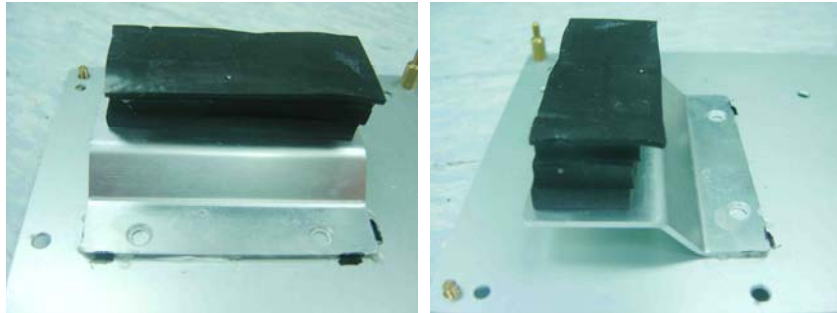
**Test Product: EPIC-KB07 A0.1**

**Sample Configuration & Quantity Under Test:**

AL plate (P/N: M16WITAS00)



AL RAM BRACKET (P/N: M19HD07000)



# Thermal Image Analysis

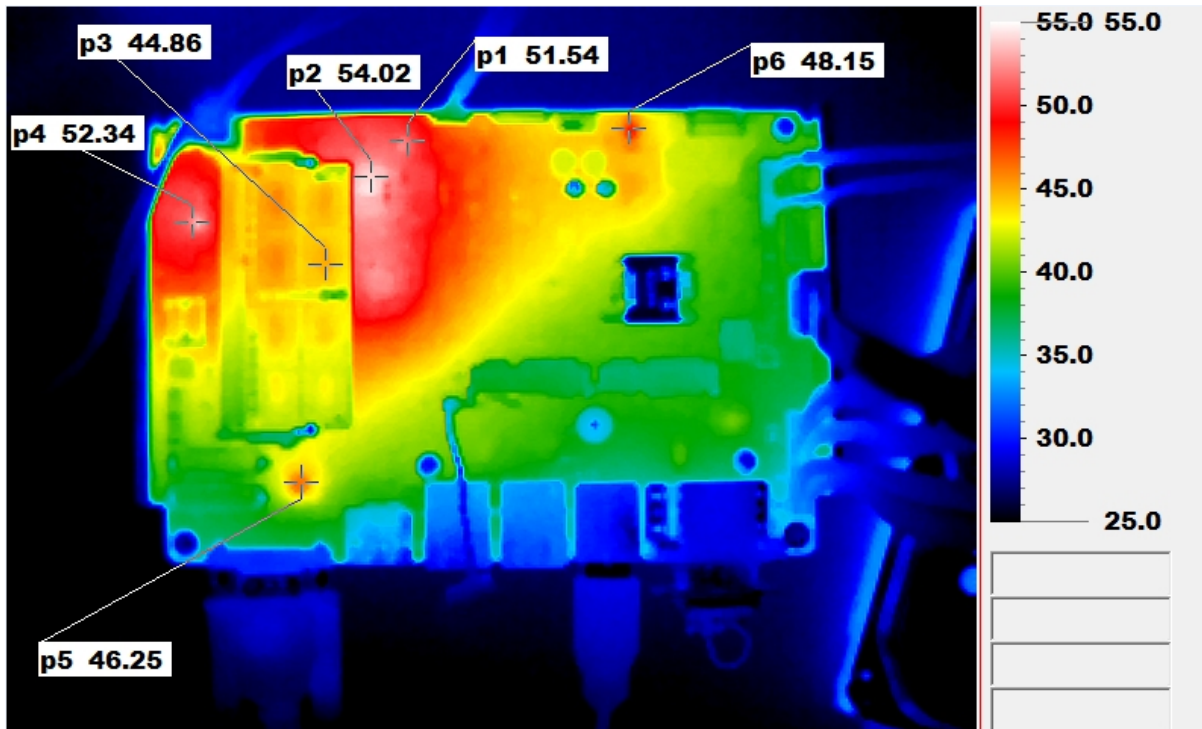
1. Test Date: 2014-05-22
2. Test Product: EPIC-KB07
3. Test Site: AAEON QE Dept.
4. Temperature Measurement:
  - 4.1. 40 Channel Thermal Recorder:
    - 4.1.1 YOKOGAWA Inc,
    - 4.2.2 Model: DA100-13-1D  
Date of Calibration: 2013/10/01  
Serial Number: 12A323190
  - 4.2. IR Scanner: Infrared Camera
    - 4.2.1 NEC Avio Infrared Technologies Co., Ltd.
    - 4.2.2 Model: Thermo GEAR G100W2-D  
Date of Calibration: 2013/01/08  
Serial Number: 1051444
5. Test Condition:

Test by DA-100: 25.0°C with Heat Sink
6. Take Picture Time:

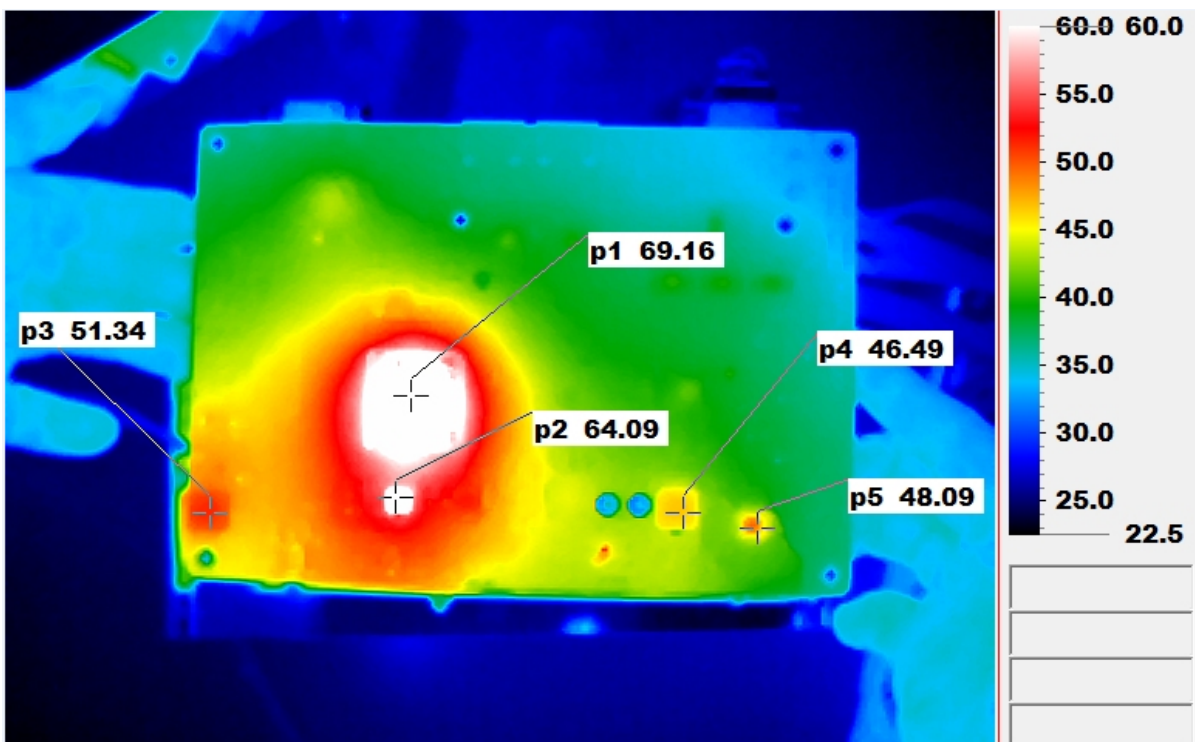
After power on 2 hours

### Temperature Profile Test:

Component Side:

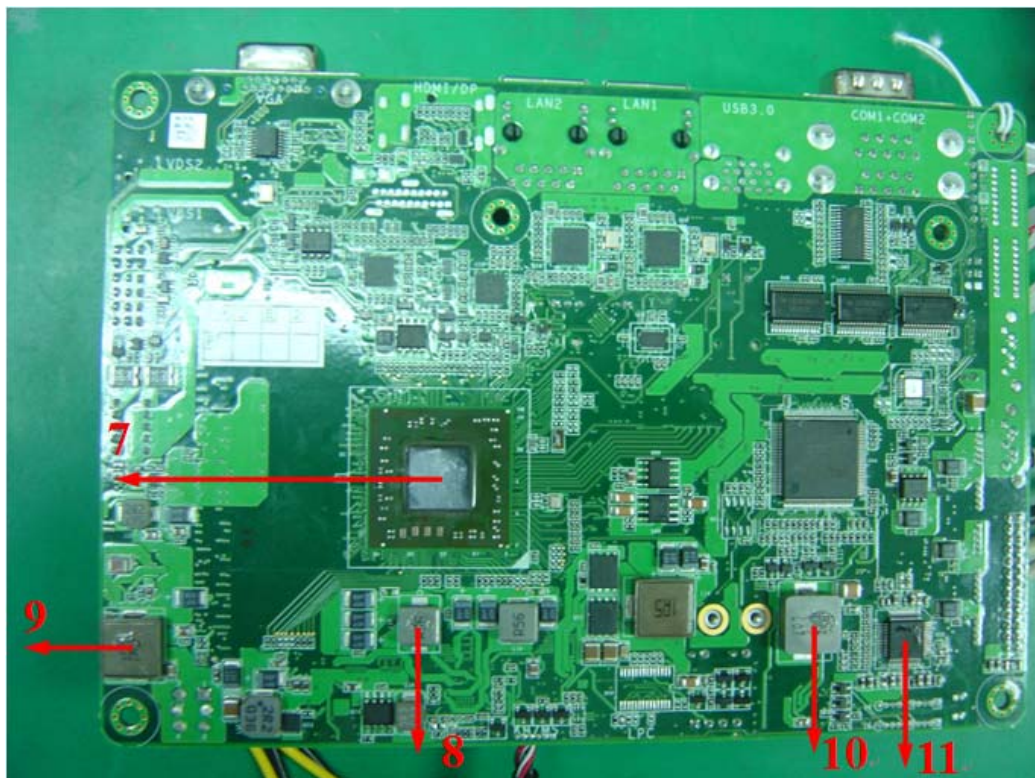
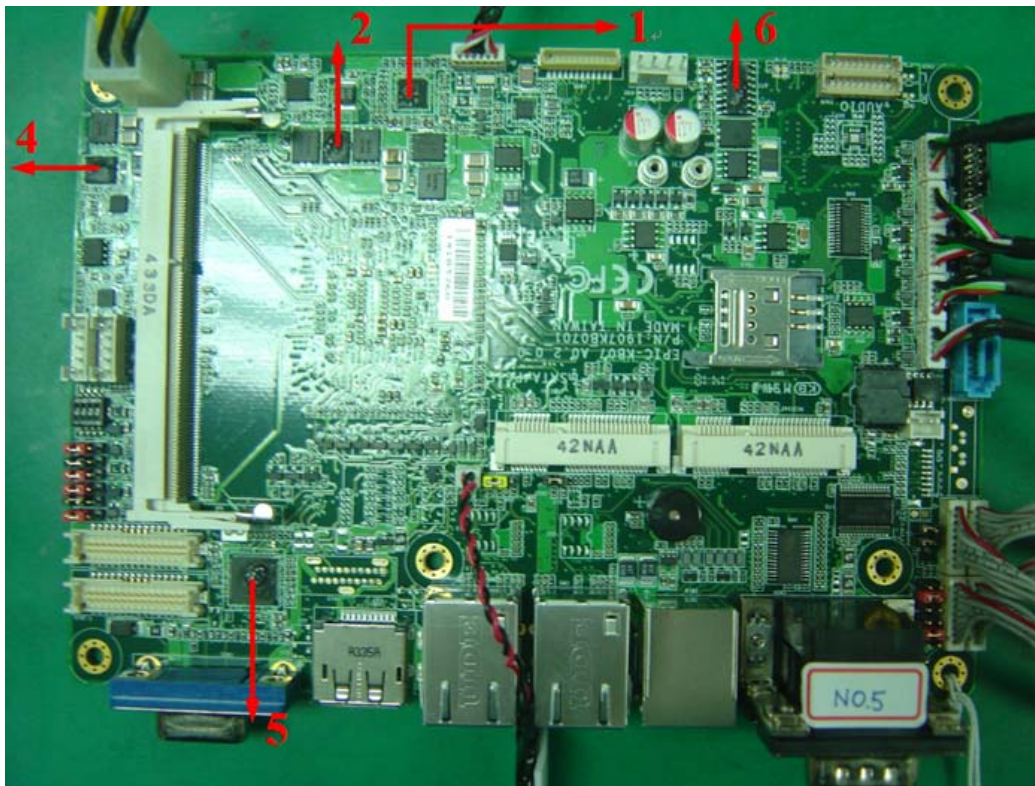


### Back Side



### Terminal Recorder :

Measuring Thermal Couple Position :



Using YOKOGAWA / DARWIN DA100-100-13-1D test

Point	Position	Describe	Tc (*1) (°C)	Tm (*2) Measured Under		Note
				25.0°C	60°C	
1	U71	(TF)IC.VID.Dual Single-Phase.SMD.O2.OZ8321LN	100	49.4	84.4	
2	Q95	(TF)PWR.SMD N-MOSFET.ON SEMI.	125	50.7	85.7	
3		DIMMP	95	44.1	79.1	
4	Q93	(TF)PWR. N-MOSFET.ON SEMI.	125	46.8	81.8	
5	U22	(TF)IC.QFN.SMD.Chrontel.CH7511B-BF(new:GBC)	125	47.6	82.6	
6	U72	(TF)IC.Low Voltage Synchronous Boost.IC2185YM	100	49.1	84.1	
7	U1	(TF)AMD BGA 769.GE420CIAJ44HM	90	45.1	80.1	
8	L18	(TF)COIL.Zenithtek.ZPWM-6030M-R56M	125	63.0	98.0	
9	L13	(TF)COIL.ZenithTek.ZPWM-1040MB-1R5M	125	44.4	79.4	
10	L20	(TF)COIL.CYNTEC.PCMB104E-4R7MS	125	44.5	79.5	
11	U58	(TF)IC. Definition.Audio SMD.REALTEK.ALC892-CG	85	37.9	72.9	

Note(\*):

1. "Tc" indicates the component's case maximum temperature value specified in its datasheet.
2. "Tm" indicates the measured Tc value under working environmental temperature within product specification.

3. Judgment Criteria:

- **Fail** :  $T_m > T_c + 5^\circ\text{C}$ ; The measured value is over specification plus margin.
- **Margin** :  $T_c + 5^\circ\text{C} > T_m > T_c - 10^\circ\text{C}$ ; The measured value is within specification with margin.  
For FANLESS system application, it is strongly recommended to add thermal dissipation design for better reliability.
- **Pass** :  $T_m < T_c - 10^\circ\text{C}$ ; The measured value is with safety margin.